



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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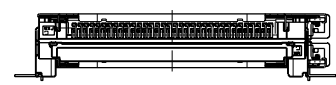
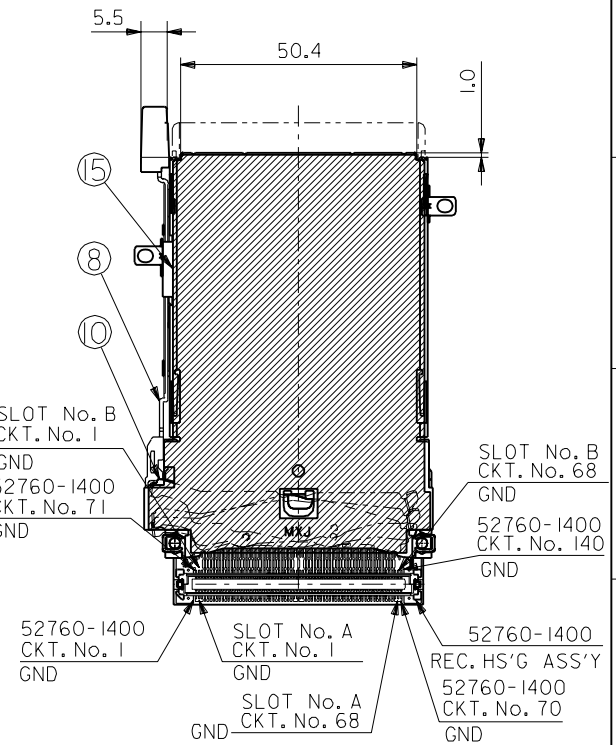
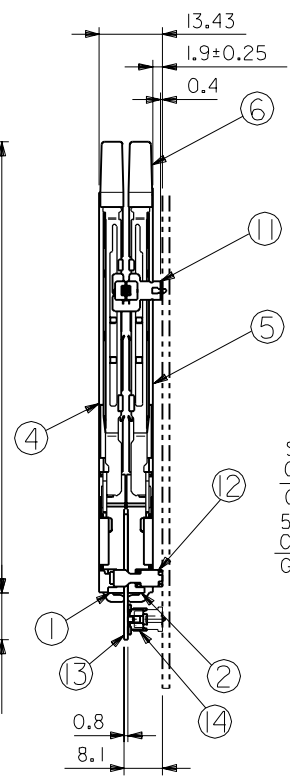
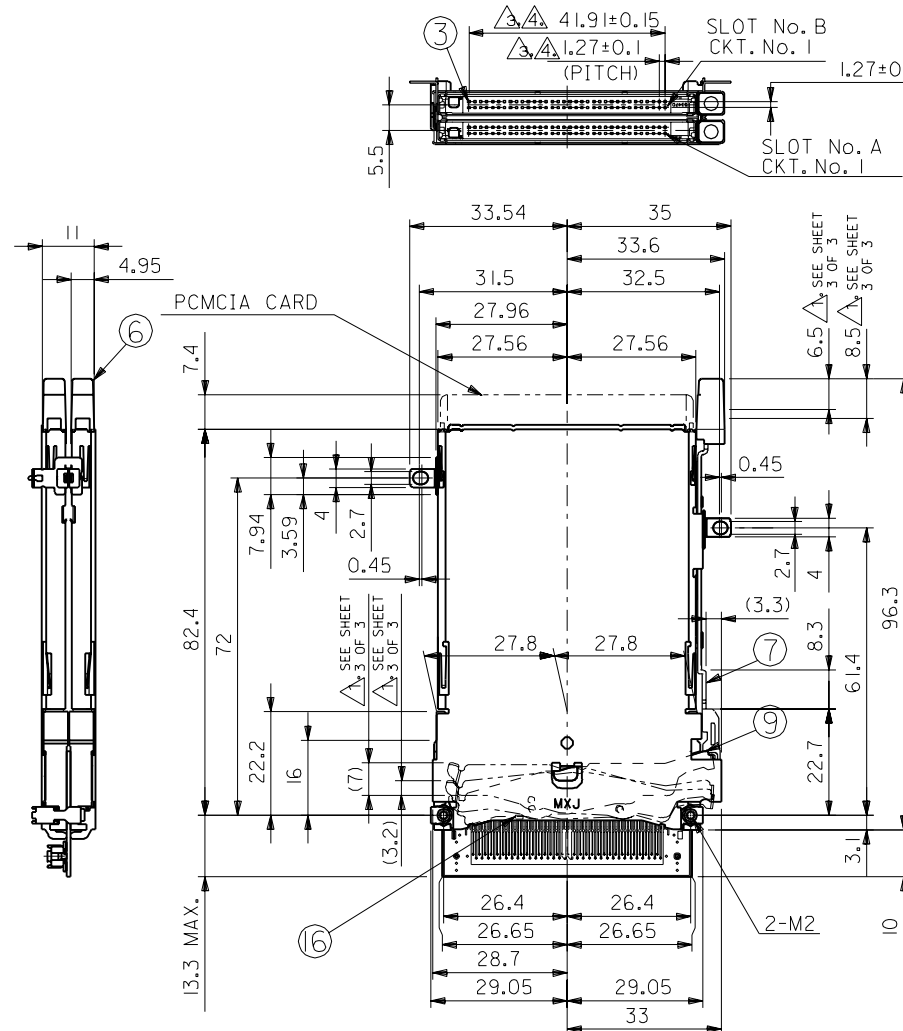
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MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING



角 度 ANGLE		±3°				材 料 MATERIAL		SHEET 3 OF 3 参照 SEE SHEET 3 OF 3	
30 以上 OVER	+0.3	B	変 更 REVISED	(J090950)	T.H.	M.S.	99/01/13	仕 上 げ SHEET 3 OF 3 参照 FINISH SEE SHEET 3 OF 3	適用電線範囲 WIRE RANGE
10 以上 30 未満 OVER 30 UNDER	+0.25	A	変 更 REVISED	(140883)	T.H.	M.S.	94/11/18	被覆外径 INS. RANGE	—
10 未満 UNDER	+0.2	O	新規作成 RELEASED	(140772)	T.H.	M.S.	94/10/21	DRAWN BY	CHK'D BY
般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD		DR.	日付 DATE	APP'D BY DATE	尺 度 SCALE	1 - 1

材料 MOLEX-JAPAN CO.,LTD.  
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称  
MEMORY CARD CONN.  
EJECT MECHANISM  
METAL SHELL TYPE

DWG. NO. SHEET 1 OF 3 REV B

SD-53524-1364

DWG. NO. SD-53524-1364

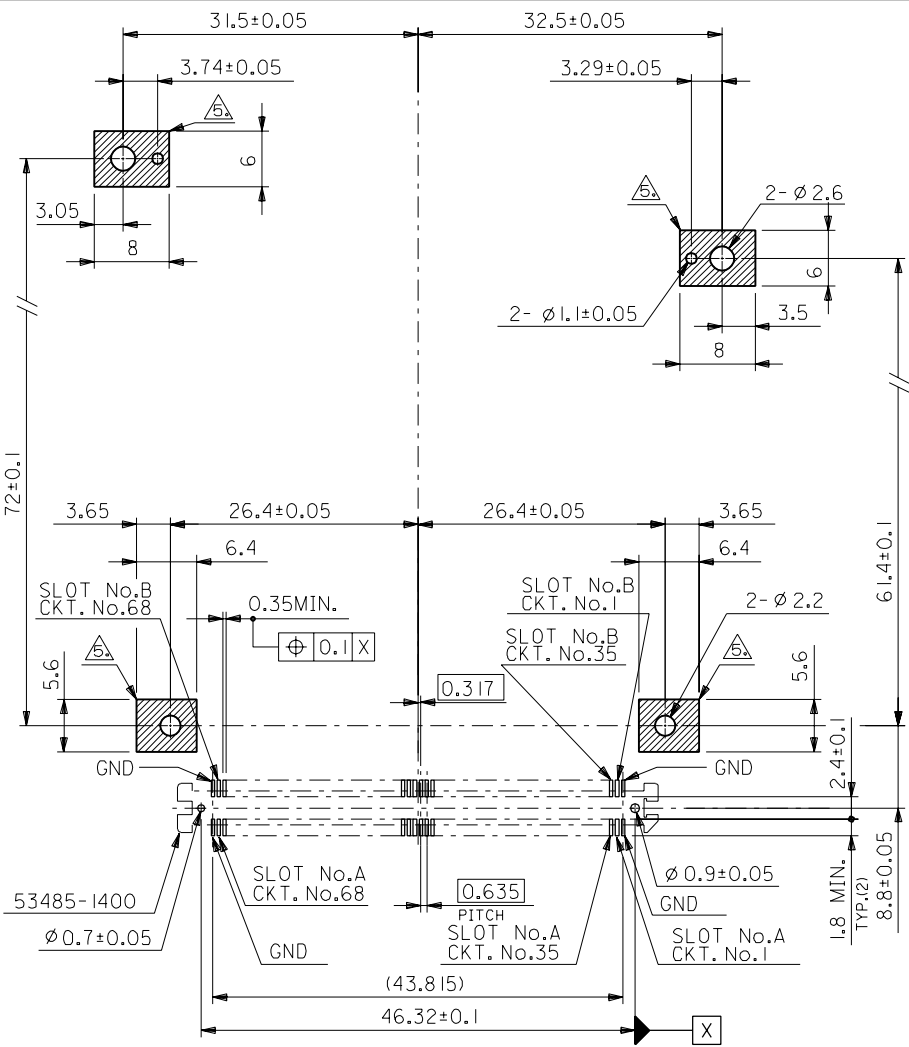
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推奨基板寸法  
RECOMMENDED PCB PATTERN LAYOUT

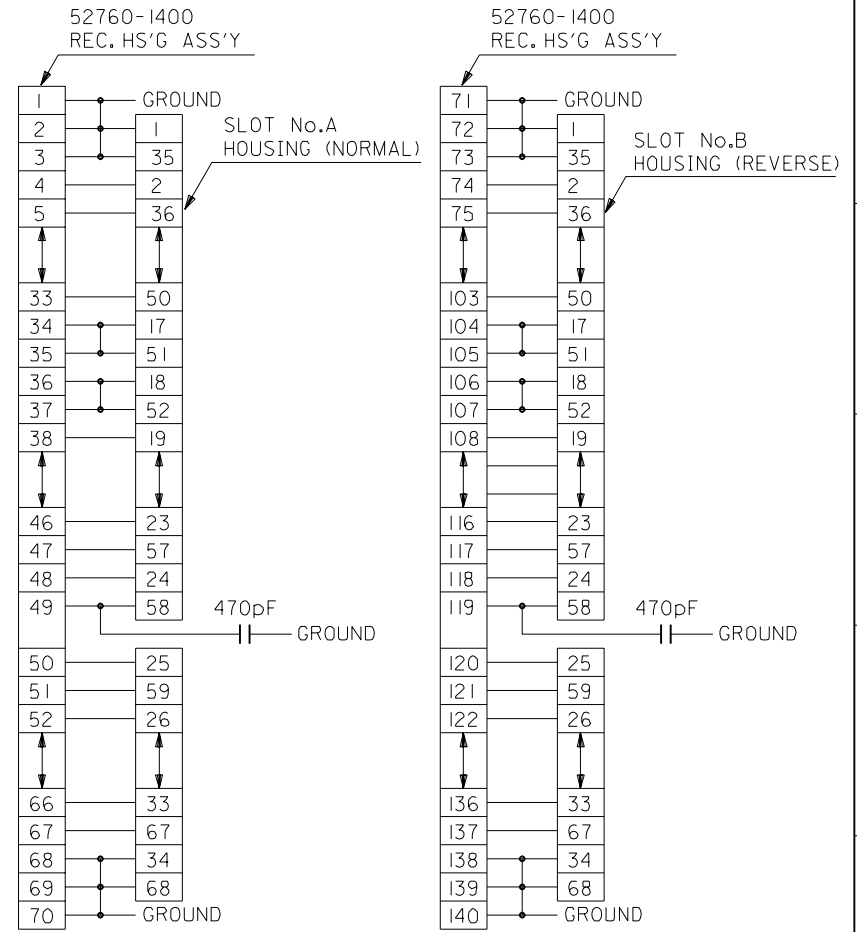


DIAGRAM A:  
CIRCUIT ASSIGNMENT DWG.

角度 ANGLE	+3°
30°以上 OVER	+0.3
10°以上 30°未満 UNDER	+0.25
未過 10° UNDER	+0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR. CHR.	日付 DATE
0	SHEET 1 OF 3 参照 SEE SHEET 1 OF 3		94/10/21
A			94/11/18
B			99/01/13

材料 MATERIAL	SHEET 3 OF 3 参照 SEE SHEET 3 OF 3
仕上げ FINISH	SHEET 3 OF 3 参照 SEE SHEET 3 OF 3
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY	CHK'D BY
H. Wata	M. Saito
APP'D BY	尺度 SCALE
Y. Hasegawa	2 - 1

MOLEX JAPAN CO., LTD. 日本モレックス株式会社
REVISION ON CAD SYSTEM
TITLE 名称
MEMORY CARD CONN. EJECT MECHANISM METAL SHELL TYPE
DWG. NO.
SHEET 2 OF 3 REV
SD-53524-1364

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EN-OIC(032)MXJ-32

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DWG. NO. SD-53524-1364

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DIMENSIONS IN METRIC DO NOT SCALE DRAWING

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注)

NOTES  
 △ ボタンストロークが 6.5mmの時、カード飛び出し量は (3.2mm)。  
 ボタンストロークが 8.5mmの時、カード飛び出し量は (7mm)。  
 WHEN BUTTON PUSH STROKE IS 6.5mm, CARD OUT BY (3.2mm).  
 WHEN BUTTON PUSH STROKE IS 8.5mm, CARD OUT BY (7mm).

△ 接点部 CONTACT AREA 金めつき : 0.1 μmMIN.  
 Au PLATING : 0.1 μmMIN.  
 パラジウムニッケルめつき, Pd/Ni=80/20(%) 0.5 μmMIN.  
 Pd-Ni PLATING, Pd/Ni=80:20(%) 0.5 μmMIN.

半田付(テ部) SOLDER TAIL AREA 半田めつき, Sn/Pb=90/10(%) 2.0 μmMIN.  
 Sn-Pb PLATING, Sn/Pb=90/10(%) 2.0 μmMIN.  
 下地めつき UNDERPLATING ニッケルめつき : 1.5 μmMIN.  
 Ni PLATING : 1.5 μmMIN.

△ ピンの倒れは、ピン根元を基準に全方向へ 0.1 MAX.とする。  
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1  
 WHEN MEASURED FROM PIN BASE.

△ ピン根元に適用する。  
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

△ 部品実装禁止範囲。  
 NO PART TO BE MOUNTED IN THESE AREAS.  
 △ 半田めつき, Sn/Pb=90/10(%) 3.0 μmMIN.  
 Sn-Pb PLATING, Sn/Pb=90/10(%) 3.0 μmMIN.  
 銅下地めつき : 1.0 μmMIN.  
 Cu UNDER PLATING : 1.0 μmMIN.

No.	品名 NAME	材料 MATERIAL	仕上げ FINISH	個数 PIECE
1	HOUSING (NORMAL)	ガラス入り耐熱樹脂 UL94V-0 LCP G.F. UL94V-0 色 : 自然色 COLOR : NATURAL	—	1
2	HOUSING (REVERSE)	ガラス入り耐熱樹脂 UL94V-0 LCP G.F. UL94V-0 色 : 自然色 COLOR : NATURAL	—	1
3	PIN	りん青銅 PHOSPHOR BRONZE	NOTES △ 参照 SEE NOTES △	136
4	METAL SHELL (FOR LEFT SIDE BUTTON)	ステンレス鋼 t 0.254 STAINLESS STEEL t 0.254	—	1
5	METAL SHELL (FOR RIGHT SIDE BUTTON)	ステンレス鋼 t 0.254 STAINLESS STEEL t 0.254	—	1
6	BUTTON	ガラス入りポリエステル UL94V-0 PBT G.F. UL94V-0 色 : 青色 COLOR : BLUE	—	2
7	PUSH ROD (FOR LEFT SIDE BUTTON)	ステンレス鋼 t 0.8 STAINLESS STEEL t 0.8	—	1
8	PUSH ROD (FOR RIGHT SIDE BUTTON)	ステンレス鋼 t 0.8 STAINLESS STEEL t 0.8	—	1
9	LEVER (FOR LEFT SIDE BUTTON)	ステンレス鋼 t 0.4 STAINLESS STEEL t 0.4	—	1
10	LEVER (FOR RIGHT SIDE BUTTON)	ステンレス鋼 t 0.4 STAINLESS STEEL t 0.4	—	1
11	FRONT BRACKET	ステンレス鋼 t 0.4 STAINLESS STEEL t 0.4	—	2
12	REAR BRACKET	冷間圧延鋼板 (SPCC) t 0.5 COLD ROLLED CARBON STEEL SHEETS t 0.5	NOTES △ 参照 SEE NOTES △	2
13	PCB	ガラス布基材エポキシ樹脂 t 0.8 GLASS FABRIC BASE, EPOXY RESIN t 0.8	—	1
14	0.635 PITCH B-T0-B S/T REC. HS'G ASS'Y	SD-52760-***0 参照 SEE SD-52760-***0	—	1
15	INSULATION SHEET	ポリエステル t 50μm POLYESTER t 50μm	—	1
16	FIXED CAPACITORS	470pF SIZE: L6X0.8	—	2

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材料 MATERIAL		表参照 SEE CHART		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH		表参照 SEE CHART		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE		—		TITLE 名称 MEMORY CARD CONN. EJECT MECHANISM METAL SHELL TYPE	
被覆外径 INS. RANGE		—		DWG. NO. SHEET 3 OF 3   REV	
DRAWN BY A. Urita	CHK'D BY Y. Saito	DATE 99/10/21	DATE 99/10/18	SD-53524-1364 B	
APP'D BY H. Hasegawa		尺 度 SCALE NONE			

角度 ANGLE	+3°	
30 以上 OVER	+0.3	B
10 以上 30 未満 UNDER	+0.25	A
10 未満 UNDER	+0.2	O
一般公差 GENERAL TOLERANCES		

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